

WAFER PROCESSING METHOD

ABSTRACT OF THE DISCLOSURE

A wafer processing method includes a pattern region detecting step, an evaluation region setting step, and an evaluation region deploying step. The pattern region detecting step is a step of detecting a period and positional information in which a substantially identical image appears in an imaged image and detecting a pattern region corresponding to one period. The evaluation region setting step is a step of detecting a position in which no metallic pattern is formed on planned dividing lines and setting the position as an evaluation region for evaluating quality of a processed groove. The evaluation region deploying step is a step of recording the position of the evaluation region in the pattern region and deploying the evaluation region at similar positions in different pattern regions.

[Fig. 2]